



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-06-23
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement
Supplier Acceptance * true Legal Declaration * Standard

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.
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Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HNZJ*Z24Q81Y	A	ZA41	2015-06-23
Amount	UoM	Unit type	ST ECOPACK Grade	
98.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.5X2.16X3.68	1	J bend	
Comment	Package: SMB CLIP (SOD 6 NEW), MD valid for CP:STPS1L40U			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HNZJ*Z24Q81Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.758	mg	supplier	die	Silicon (Si)	7440-21-3		0.644	mg	849734	6520
				supplier	metallization	Aluminium (Al)	7429-90-5		0.026	mg	34574	265
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1330	10
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1330	10
				supplier	metallization	Nickel (Ni)	7440-02-0		0.003	mg	3989	31
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	5319	41
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1330	10
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.004	mg	5319	41
				supplier	polymer die coating	Durimide	proprietary		0.074	mg	97074	745
Leadframe	Copper and its alloy	39.531	mg	Supplier	Alloy	Copper (Cu)	7440-50-8		39.511	mg	999490	399622
				Supplier	Alloy	Zinc (Zn)	7440-66-6		0.002	mg	51	20
				Supplier	Alloy	Iron (Fe)	7439-89-6		0.004	mg	102	41
				Supplier	Alloy	Phosphorus (P)	12185-10-3		0.014	mg	357	143
Die attach	Other organic material	3.328	mg	Supplier	soft solder	Silver (Ag)	7440-22-4		0.083	mg	24856	837
				Supplier	soft solder	Tin (Sn)	7440-31-5		0.166	mg	50015	1684
				Supplier	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high me	3.079	mg	925129	31143
Encapsulation	Other organic material	52.632	mg	Supplier	Molding Compound	silica fused	7631-86-9		38.947	mg	739994	393918
				Supplier	Molding Compound	silica quartz	14808-60-7		10.526	mg	199988	106459
				Supplier	Molding Compound	phenolic resin	9003-35-4		2.632	mg	50012	26622
				Supplier	Molding Compound	carbon black	1333-86-4		0.527	mg	10006	5327
Finishing	Other inorganic material	1.751	mg	Supplier	connection coating	Sn	7440-31-5		1.751	mg	1000000	17714